



PDM: Rev:K

Printed: Jul 31, 2006

FCIconnect.com

3 |

NOTES:

´1.) MAT'L:

HOUSING: LCP

**CONTACT:** COPPER ALLOY

**PLATING** 

CONTACT: (SEE TABLE ON SHEET1) SOLDER BALL: (SEE TABLE ON SHEET1) EUTECTIC SnPb OR LEAD FREE 95.5Sn/4Aq/0.5Cu

- (2.)SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
- (3.) MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.
- (4.) PLATING FOR -2XX SERIES DASH NOS: Au OVER Ni WITH SPECIAL CONTACT GEOMETRY TO MEET REQUIREMENTS OF TELCORDIA GR-1217-CORE: CENTRAL OFFICE ENVIRONMENT.
- (5.) FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THERFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION
- (6) THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION

mat'l. code							surface / tolerance						projection			product family								
SEE NOTE 1						ASME Y14.5 V ASME Y14.5						ф.д		MEG-ARRAY										
ltr	ecn r	סר	dr	date		tolera	nces	unless	nless otherwise specified						title									
K						angle	s la	,	±.3 :±.13		MM		6mm RECPT. ASSY.											
						0° ±2°		ĺ																
									XXX.	±.051		scale	2	:1			10×40= 400 POS.							
					дr	D	WAUGHEN		1.5	.98				dwg r	no			st	neet	3	of 3	size		
						engr	7	LEM	ΚE	1.5	1.5.98		FCi			7.4700								
						chr	1	T LEMKE		1.5.98		' <b>3</b>			74388 A4							H4		
						appd		T LEMKE		1.5.98				type CUSTOMER Drawing						ving				
shee	sheet		ion																					
index		sheet																						

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STATUS Released

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1

form: A4mmXLc